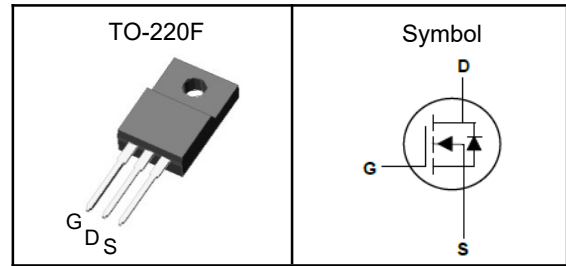


N-Channel Enhancement Mode MOSFET
Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant
- 100% UIS and Rg Tested

Applications

- Power Management in Desktop Computer
- DC/DC Converters

Pin Description


V_{DSS}	650	V
$R_{DS(ON)-Typ}$	460	m Ω
I_D	16	A

Absolute Maximum Ratings($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	650	V
V_{GSS}	Gate-Source Voltage	± 30	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
E_{AS}	Single Pulse Avalanche Energy ^③	698	mJ
$I_{DM}^{①}$	Pulse Drain Current Tested	64	A
I_D	Continuous Drain Current	$T_c=25^\circ\text{C}$	A
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	W

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ^①	62.5	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ^①	1.64	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150 $^\circ\text{C}$.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.



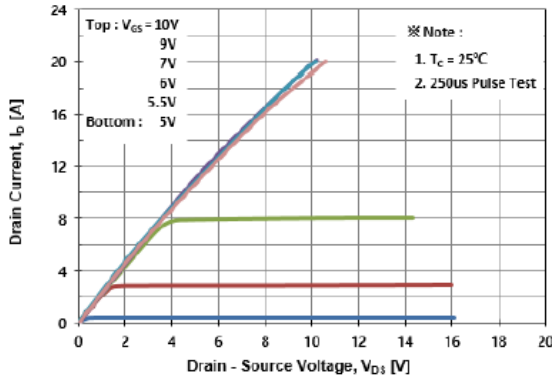
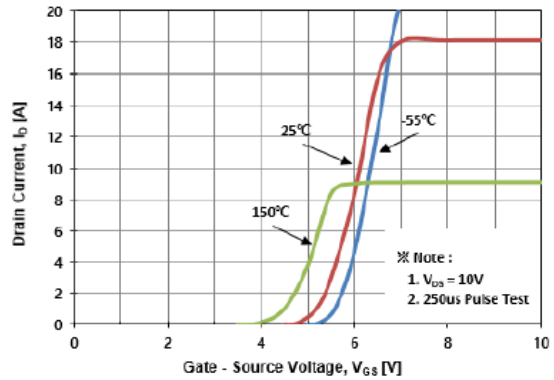
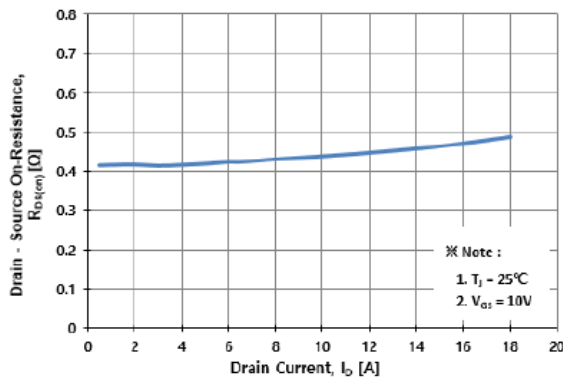
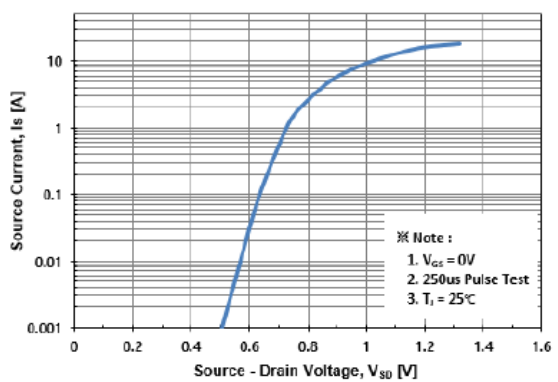
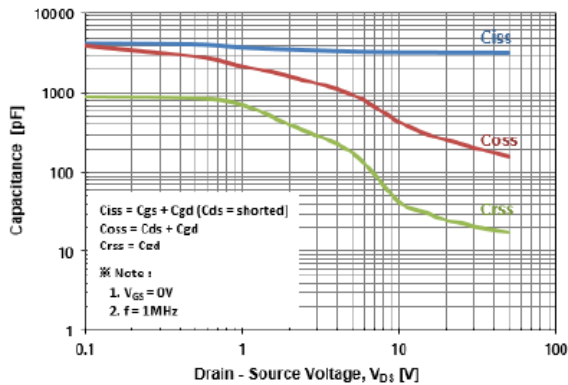
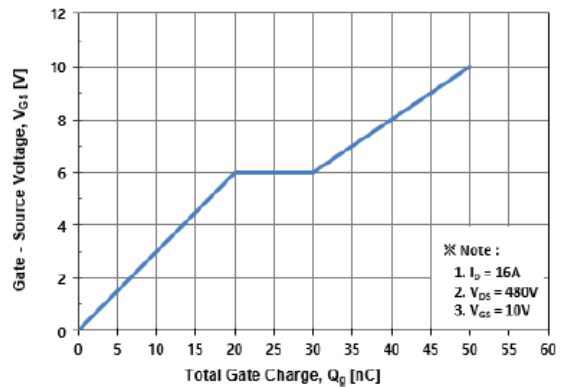
N-Channel Enhancement Mode MOSFET

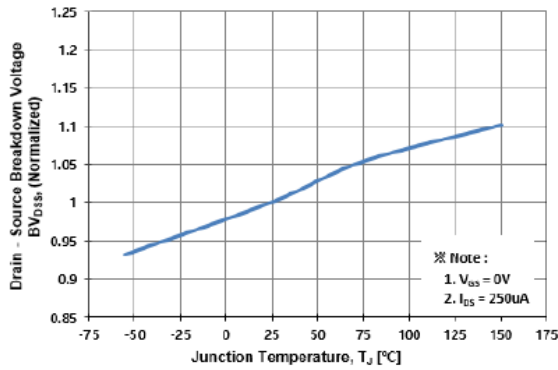
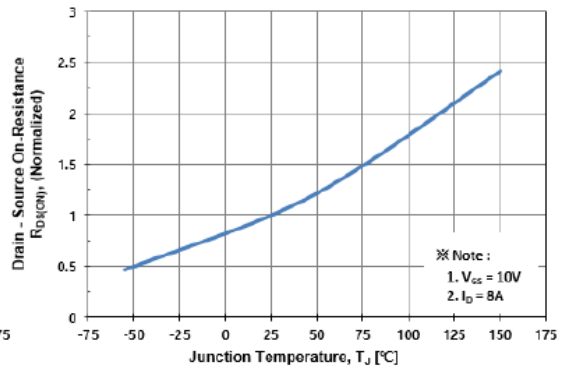
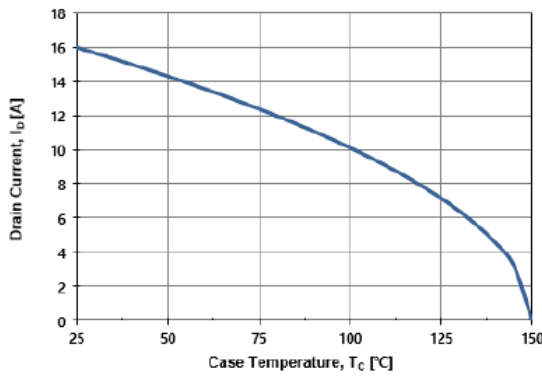
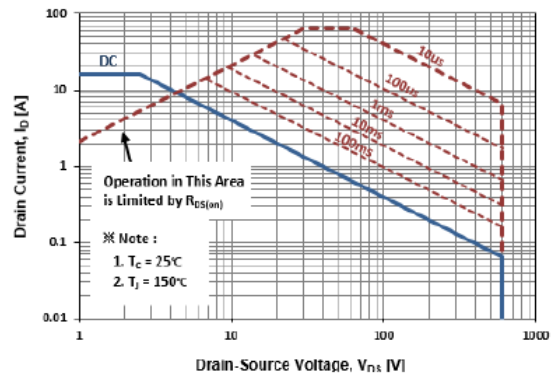
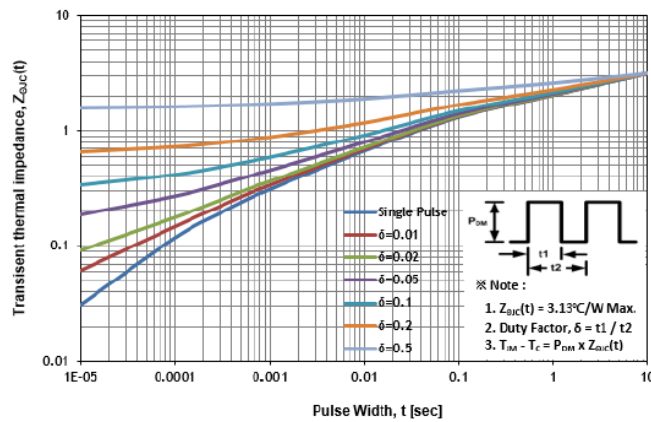
Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	650	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=650V, V_{GS}=0V$	---	---	1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	3	---	5	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	± 100	nA
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_D=8A$	---	460	520	$m\Omega$
Dynamic Characteristics ^⑤						
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=25V,$ $Freq.=1MHz$	---	3325	---	pF
C_{oss}	Output Capacitance		---	225	---	
C_{rss}	Reverse Transfer Capacitance		---	22	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{DD}=325V, R_G=25\Omega,$ $I_D=16A$	---	175	---	nS
T_r	Turn-on Rise Time		---	121	---	
$T_{d(off)}$	Turn-off Delay Time		---	373	---	
T_f	Turn-off Fall Time		---	64	---	
Q_g	Total Gate Charge	$V_{DS}=520V,$ $V_{GS}=10V, I_D=16A$	---	50	---	nC
Q_{gs}	Gate-Source Charge		---	20	---	
Q_{gd}	Gate-Drain Charge		---	10	---	
Source-Drain Characteristics ($T_J=25^{\circ}\text{C}$)						
V_{SD}	Diode Forward Voltage ₂	$V_{GS}=0V, I_S=16A, T_J=25^{\circ}\text{C}$	---	---	1.4	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0V, I_S=16A,$ $di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	---	484	---	nS
Q_{rr}	Reverse Recovery Charge		---	1.62	---	nC

Note ④ : Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

N-Channel Enhancement Mode MOSFET
Typical Characteristics
Fig. 1 Typical Output Characteristics

Fig. 2 Typical Output Characteristics

Fig. 3 On-Resistance Variation with Drain Current and Gate Voltage

Fig. 4 Body Diode Forward Voltage Variation with Source Current

Fig. 5 Typical Capacitance Characteristics

Fig. 6 Typical Total Gate Charge Characteristics


N-Channel Enhancement Mode MOSFET
Fig. 7 Breakdown Voltage Variation vs. Temperature

Fig. 8 On-Resistance Variation vs. Temperature

Fig. 9 Maximum Drain Current vs. Case Temperature

Fig. 10 Maximum Safe Operating Area

Fig. 11 Transient Thermal Impedance


N-Channel Enhancement Mode MOSFET
TO-220F Package Outline Data
